

**Amendments to the Claims**

1. (CURRENTLY AMENDED)      An integrated circuit device ~~(110)~~ comprising:  
an integrated circuit ~~(130)~~ having a plurality of grounding pads, signal pads, and  
power pads; and a package ~~(110)~~ for mounting the integrated circuit and including a  
conductive path ~~(140)~~ having at least one reference trace surrounding the integrated  
circuit and having a grounding arch ~~(170)~~, disposed over the integrated circuit ~~(130)~~.
2. (ORIGINAL)      The integrated circuit device of claim 1 wherein the reference  
trace is coupled to at least one of the following: a voltage reference, a ground  
reference.
3. (ORIGINAL)      The integrated circuit device of claim 1 wherein, the grounding  
arch has an area comparable to the area of the integrated circuit device.
4. (CURRENTLY AMENDED)      The integrated circuit device of claim 1 wherein  
the grounding arch is comprised of metal tape ~~(160)~~ laminated with a dielectric  
material ~~(145)~~.
5. (ORIGINAL)      The integrated circuit device of claim 4, wherein the grounding  
arch has a predetermined thickness thereby providing sufficient structure preventing  
electrical contact between the grounding arch and wire bonds.
6. (CURRENTLY AMENDED)      The integrated circuit device of claim 1 wherein  
the grounding arch is coupled to at least one grounding location on the integrated  
circuit device, wherein the grounding location includes, the grounding trace ~~(250a~~,  
~~250e)~~ and grounding pads ~~(225)~~.
7. (CURRENTLY AMENDED)      The integrated circuit device of claim 6 wherein  
the grounding location further includes a location about a center region ~~(250b)~~ on the  
integrated circuit device.

8. (ORIGINAL) The integrated circuit device of claim 5 wherein the grounding arch comprises conductors of a highly conductive material selected from: copper, gold, silver, aluminum and an alloys thereof.

9. (ORIGINAL) The integrated circuit device of claim 5 wherein the highly conductive material is in a form including solid tape, mesh, and woven wire bonds.

10. (ORIGINAL)) The integrated circuit device of claim 1 wherein the grounding arch is coupled to the grounding location with at least one of the following: conductive glue, solder, eutectic metal bond, a thermo-compression bond.

11. (ORIGINAL) The integrated circuit device of claim 3, wherein the dielectric material is selected from at least one of the following: epoxy, polyimide, polyamide, solder mask, PTFE, and TEFLON™.

12. (CURRENTLY AMENDED) A method ~~(600)~~ for controlling impedance of bond wires in packaging a semiconductor device die in a package, the method comprising: defining locations ~~(605)~~ of signal and power/ground pads on the device die; defining grounding trace ~~(605)~~ locations on the package; bonding the signal pads and power/ground pads ~~(610)~~ of the device die; providing a conductive path including a ground arch over the bond wires and grounding trace locations ~~(615, 620)~~; and encapsulating the device die and ground arch ~~(625)~~.

13. (ORIGINAL) The method of claim 12 wherein providing a conductive path further includes, rotating the package a pre-determined amount; and providing an additional ground arch.

14. (ORIGINAL) The method of claim 13 wherein the pre-determined amount is about 90°.

15. (ORIGINAL)      The method of claim 13, wherein providing an additional ground arch is a function of device design, package size, number of wire bonds, and a desired impedance.

16. (ORIGINAL)      The method of claim 15, wherein the desired impedance is function of a ground arch distance from a wire bond.